

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
24 June 2004 (24.06.2004)

PCT

(10) International Publication Number
WO 2004/053986 A1

(51) International Patent Classification⁷: H01L 23/64,
23/498

GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR,
KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK,
MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT,
RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR,
TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(21) International Application Number:
PCT/IB2003/005616

(22) International Filing Date: 4 December 2003 (04.12.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/432,482 10 December 2002 (10.12.2002) US

(71) Applicant (for all designated States except US): KONINKLIJKE PHILIPS ELECTRONICS N.V. [NL/NL];
Groenewoudseweg 1, NL-5621 BA Eindhoven (NL).

(72) Inventor; and

(75) Inventor/Applicant (for US only): WYLAND, Chris
[US/US]; 1109 McKay Drive, M/S-41SJ, San Jose, CA
95131 (US).

(74) Common Representative: KONINKLIJKE PHILIPS
ELECTRONICS N.V.; c/o LESTER, Shannon, 1109
McKay Drive, M/S-41SJ, San Jose, CA 95131 (US).

(81) Designated States (national): AE, AG, AL, AM, AT, AU,
AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU,
CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE,
GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR,
KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK,
MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT,
RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR,
TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW, ARIPO patent
(BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM,
ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ,
TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK,
EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO,
SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA,
GN, GQ, GW, ML, MR, NE, SN, TD, TG)

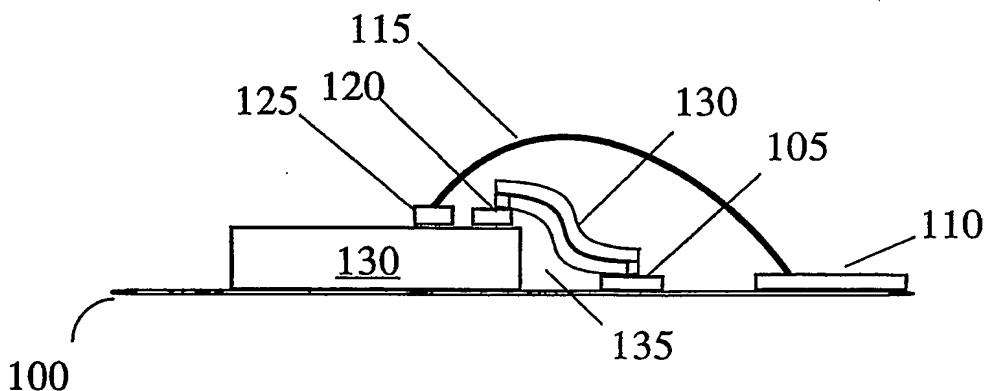
(84) Designated States (regional): ARIPO patent (BW, GH,
GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW),
Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),
European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE,
ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE,
SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA,
GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Declaration under Rule 4.17:

— as to applicant's entitlement to apply for and be granted
a patent (Rule 4.17(ii)) for the following designations AE,
AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH,
CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES,
FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE,
KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG,
MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT,
RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT,
TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW, ARIPO patent
(BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM,
ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ,
TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK,
EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO,
SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA,
GN, GQ, GW, ML, MR, NE, SN, TD, TG)

[Continued on next page]

(54) Title: HIGH DENSITY PACKAGE INTERCONNECT POWER AND GROUND STRAP AND METHOD THEREFOR



WO 2004/053986 A1

(57) **Abstract:** One aspect of the present invention relates to reducing the impedance of the paths connecting the power or ground of a device and a BGA package. In a particular example implementation, impedance of the signal bond wires is controlled by placing a ground strap (130) at a predetermined distance from the signal bond wires (115). In a related example embodiment, a low impedance power or ground connection is made between a device die (140) and package in close proximity to wire bonds (115). An integrated circuit (140) includes a plurality of grounding pads, signal pads, power pads and a package for mounting the integrated circuit. The package (100) comprises a plurality of pad landings (110), a grounding ring (105) surrounding the integrated circuit (140); and a grounding strap (130) coupling the grounding ring (105) to the grounding pads (120) of the integrated circuit.